

AMENDMENTS TO THE CLAIMS:

1. (Currently Amended) A method for carbon nanotube emitter surface treatment, which is used on a carbon nanotube electronic electronics source for increasing the number of carbon nanotubes nanotube exposed on a triode structure or any other surface structure of a carbon nanotube field emission display (CNT-FED), CNT-FED, then the method can advance the current density and intensity of CNT emitter; the method for carbon nanotube emitter surface treatment comprising the steps of:
coating an adhesive material on the surface of said CNT-FED;
heating said adhesive material for adhibiting the surface of said CNT-FED; and
removing impurities on the surface of said CNT-FED by lifting said adhesive material off.
2. (Currently Amended) The method for carbon nanotube emitter surface treatment as recited claimed in claim 1, wherein said adhesive material is selected from the group consisting of a hot melt glue, or a soluble material, an organic material, an inorganic material and a strippable material.
3. (Currently Amended) The method for carbon nanotube emitter surface treatment as recited claimed in claim 1, wherein said adhesive material sticks on said carbon nanotube electronic electronics source.
4. (Currently Amended) The method for carbon nanotube emitter surface treatment as recited claimed in claim 3, wherein said carbon nanotube electronic source is set between a cathode plate and a gate existed in said triode structure.

5. (Currently Amended) A method for carbon nanotube emitter surface treatment, which is used on a carbon nanotube electronic electronics source for increasing the number of carbon nanotubes nanotube exposed on a triode structure or any other surface structure of a carbon nanotube field emission display (CNT-FED), CNT-FED, then the method can advance the current density and intensity of CNT-emitter; the method for carbon nanotube emitter surface treatment comprising the steps of:
 - coating an activator on the surface of said CNT-FED;
 - coating an adhesive material on said activator;
 - pressing said adhesive material for adhitting the surface; and
 - removing impurities on the surface of said CNT-FED by lifting said adhesive material off.
6. (Currently Amended) The method for carbon nanotube emitter surface treatment as recited claimed in claim 5, wherein said activator is an interface activator, a [[,]] surfactant or a release agent.
7. (Currently Amended) The method for carbon nanotube emitter surface treatment as recited claimed in claim 5, wherein said adhesive material is selected from the group consisting of a hot melt glue, or a soluble material, an organic material, an inorganic material and a strippable material.
8. (Currently Amended) The method for carbon nanotube emitter surface treatment as recited claimed in claim 5, wherein said step of pressing said adhesive material for adhitting the surface of said CNT-FED is achieved by a pressing machine.
9. (Currently Amended) The method for carbon nanotube emitter surface treatment as

recited claimed in claim 5, wherein said adhesive material sticks on said carbon nanotube electronic electronics source.

10. (Currently Amended) The method for carbon nanotube emitter surface treatment as recited claimed in claim 9, wherein said carbon nanotube electronic source is set between a cathode plate and a gate ~~existed~~ in said triode structure.